

## PATENT APPLICATION Do. No. 3981-34

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of:

Joel R. Goergen

Serial No.:

10/068,745

Examiner:

Not yet assigned

Filing Date:

February 5, 2002

Group Art Unit:

2841

Title:

METHOD OF FABRICATING A HIGH-LAYER-COUNT

**BACKPLANE** 

#### TRANSMITTAL LETTER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Enclosed for filing in the above-referenced application are the following:

X Information Disclosure Statement

PTO Form 1449

 $\boxtimes$ References cited (2)

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Customer No. 50272

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: November 4, 2003

fallow Te Lauren Ballard-Gemmell



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nventor(s):

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METHOD OF FABRICATING A HIGH-LAYER-COUNT BACKPLANE

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#### INFORMATION DISCLOSURE STATEMENT

Sir:								
	This Info	is Information Disclosure Statement is submitted:						
	$\boxtimes$	under 37 CFR 1.97 (b); or						
		(Within three months of filing national application; or date of entry of International application;						
	or b	efore mailing date of first office action on the merits; whichever occurs last)						
		under 37 CFR 1.97 (c) together with either a:						
		Statement under 37 CFR 1.97 (e), or						
		a \$180 fee under 37 CFR 1.17 (p); or						
		(After mailing of first Office Action, but prior to Notice of Allowance or Final Office Action)						
		under 37 CFR 1.97 (d) together with:						
		Statement under 37 CFR 1.97 (e), and						
		a \$180.00 fee set forth in 37 CFR 1.17 (p).						
		(Filed after final action or notice of allowance, whichever occurs first, but before payment of						
the issue	e fee)							
	[XI	Applicant(s) submit herewith Form PTO 1449- Information Disclosure Citation together with						
•	•	publications or other information of which applicant(s) are aware, which applicant(s) believe(s)						
		o the examination of this application and for which there may be a duty to disclose in accordance						
with 37	CFR 1.56	).						
	It is rea	pasted that the information disclosed harain be made of record in this application						
	it is requ	sested that the information disclosed herein be made of record in this application.						

Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.

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Respectfully submitted,

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Date: November 4, 2003

Lauren Ballard-Gemmell



Exam

## PATENT APPLICATION

Sub

3981-034 Joel R. Goergen February 5, 2002

Document

Serial No. 10/068,745

Group: 2841

# INFORMATION DISCLOSURE CITATION FORM PTO-1449 (Modified)

## U.S. PATENT DOCUMENTS

Issue

<u>Init</u>	<u>Ref</u>	Number	<u>Date</u>	<u>Name</u>	Class	Class		
		<u>FO</u> F	REIGN PATENT	DOCUMENTS				
Exam <u>Init</u>	Ref	Document <u>Number</u>	Publication <u>Date</u>	Country	<u>Name</u>			
			OTHER DOCU	JMENTS				
Exam <u>Init</u>								
		Markstein, H.W.: <i>Impedances Dictate Backplanes</i> , Electronic Design, Packaging and Production; Vol. 33, No. 12; December 1, 1993, pp. 38-40.						
		Markstein, H.W.: Packaging for High-Speed Logic Electronic Packaging and Production, No. 9, September 27, 1987 pp. 48-50						
Examin	er:							
Date Co	nsidered:							